AMENDMENT TO THE CLAIMS

Claims 1-6 (cancelled)

7. (Currently Amended) A glide head comprising:

a glide body including a leading edge, a trailing edge and a contoured surface having a raised bearing surface elevated from a recessed bearing surface;

at least one thermal transducer fabricated on the raised bearing surface having a surface portion extending along the raised bearing surface to form a glide interface to detect asperities and the at least one thermal transducer being in electrical contact with an electrically conductive pad proximate to the trailing edge of the glide body; and

a conductive strip conductively coupled to the at least one thermal transducer and the conductive pad to provide an electrical contact between the at least one thermal transducer and the conductive pad.

Claim 8 (cancelled)

9. (Previously Presented) A glide head comprising:

a glide body including a leading edge, a trailing edge and a contoured surface having a raised bearing surface elevated from a recessed bearing surface; and

at least one thermal transducer fabricated on the raised bearing surface having a surface portion extending along the raised bearing surface to form a glide interface to detect asperities wherein the at least one thermal transducer extends along at least half of a length distance between the leading edge and the trailing edge of the glide body.

Claims 10-11 (cancelled)

12. (Previously Presented) A glide head comprising:

a glide body including a leading edge, a trailing edge and a contoured surface having a raised bearing surface elevated from a recessed bearing surface; and

a plurality of thermal transducers including at least one thermal transducer fabricated on the raised bearing surface having a surface portion extending along the raised bearing surface to form a glide interface to detect asperities wherein the plurality of thermal transducers comprise a first thermal transducer and a second thermal transducer and the first and second thermal transducers share a common electrical ground.

13. (Previously Presented) A glide head comprising:

a glide body including a leading edge, a trailing edge and a contoured surface having a raised bearing surface elevated from a recessed bearing surface; and

a plurality of thermal transducers including at least one thermal transducer fabricated on the raised bearing surface having a surface portion extending along the raised bearing surface to form a glide interface to detect asperities wherein the plurality of thermal transducers are spaced along the raised bearing surface and the glide head further comprises electrically conductive strips in electrical contact with the plurality of thermal transducers, the strips being formed on the recessed bearing surface offset from the raised bearing surface.

Claims 14-17 (Cancelled)

18. (Previously Presented) A method of fabricating a glide head from a wafer comprising;

slicing a plurality of glide bodies from the wafer; and

depositing thermal transducers on the plurality of glide bodies sliced from the wafer.

Claims 19-20 (cancelled)

21. (Previously Presented) The method of claim 18 and further comprising:

fabricating air bearing surfaces on the plurality of glide bodies sliced from the wafer including a raised bearing surface and a recessed bearing surface prior to depositing the thermal transducers; and

depositing the thermal transducers on the raised bearing surfaces of the plurality of glide bodies sliced from the wafer.

Claims 22-29 (cancelled)